

1ST CALL FOR PAPERS

ABOUT EPTC

The 24th IEEE Electronics Packaging Technology Conference (EPTC2022) is an international event organized by the IEEE RS/EPS/EDS Singapore Chapters and co-sponsored by IEEE Electronics Packaging Society (EPS). EPTC2022 conference will feature keynotes, technical sessions, technology talks, virtual exhibition corners and networking activities. It aims to provide a platform to cover the technology developments in the complete spectrum of electronics packaging from design to manufacturing. Since its inauguration in 1997, EPTC has established a highly reputed electronics packaging conference in Asia and selected as an EPS flagship conference in the Asia-Pacific Region 10, covering diverse areas of electronic packaging technology topics.

CONFERENCE TOPICS

You are invited to submit abstract(s) on new research and developments in the following packaging categories:

Advanced Packaging
TSV/Wafer Level Packaging
Interconnection Technologies
Emerging Technologies
Materials and Processing
Assembly and Manufacturing Technology
Advanced Materials and Process Manufacturing Technology
Electrical Simulation & Characterization
Mechanical Simulation & Characterization
Thermal Characterization & Cooling Solutions
Quality, Reliability & Failure Analysis
Advanced Optoelectronics and Displays
Smart Manufacturing and Packaging Equipment Technology

IMPORTANT DATES

Online abstract submission start April 20, 2022
Closing of abstract submission June 30, 2022
Notification of acceptance August 1, 2022

Please check on <http://www.eptc-ieee.net> for the latest updates.

ABSTRACT AND PAPER SUBMISSION

You are invited to submit an abstract between 500–750 words long and clearly state the purpose, methodology, results (which must include data, drawings, graphs and photographs) and conclusions

of the work. Additional details on abstracts submission can be found on the EPTC website. Abstracts must be received by June 30, 2022. Your submission must be cleared by your management and co-authors as applicable and include the authors' affiliations and e-mail addresses. All submissions should be made in English, either in pdf or MS Words format. Please select the appropriate technical committee as per your abstract content from the drop-down list so that the right technical committee can evaluate your submission for acceptance. Accepted abstracts will be notified for the full paper submission with instructions for publication by August 1, 2022. At the discretion of the technical committee, submitted abstracts may be considered for interactive presentation. The final manuscript for publication in the conference proceedings is due on September 10, 2022. The conference proceeding is an official IEEE publication, and the accepted papers that are registered and presented (oral & interactive) will be available in IEEE Xplore.

BEST PAPER AWARDS

Awards in the form of cash and certificates will be given to the best oral papers from Academia, Industry and Students. More details are available on the EPTC website.

CALL FOR TECHNOLOGY TALKS

In the last EPTC 2021, Technology Talks by industry and academics experts in advanced packaging have been introduced. It has a tremendous response from the EPTC attendees. We are inviting industry and academic experts in packaging R&D and manufacturing supplier industries (materials, equipment and services) on technology innovation, challenges, potential gaps, product and services road map. More details are updated on the conference website, and proposals for technology talks can be submitted at technicalchair@eptc-ieee.net.

CALL FOR PROFESSIONAL DEVELOPMENT COURSES

EPTC2022 would like to offer PDC from the industry and academics experts in advanced packaging. We are inviting industry and academic experts in Advanced packaging applications. More details are updated on the conference website, and proposals for PDC can be submitted at pdccair@eptc-ieee.net.

CALL FOR EXHIBITION / SPONSORSHIPS

Detailed exhibition and sponsorship opportunities are available on the conference website. For enquiries, please e-mail exhibition@eptc-ieee.net or sponsorship@eptc-ieee.net.

EPTC 2023: Website: <http://www.eptc-ieee.net> **E-mail:** secretariat@eptc-ieee.net **Join us on LinkedIn** [EPTC OC]



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